

Failure Analysis Lab

For Non-destructive Inspection and Failure Detection

ROOT CAUSE ANALYSIS WITH STATE-OF-THE-ART HIGH-RESOLUTION TOOLS AND TECHNIQUES

2D/3D X-RAY & CT SCAN IMAGING

- Digital X-ray with < 100nm feature recognition
- Digital Zoom up to 35,500X
- Defect detection using 3D Image Sectioning
- Automated X-ray void detection & measurement

INFRARED THERMAL IMAGING

- 320 x 240 pixel live IR image resolution
- 3.1 Mega-pixel visible spectrum picture-in-picture
- Real-time data acquisition and analysis

DIGITAL MICROSCOPY

- Extremely high resolution up to 20,000 x 20,000 pixels
- 0.1x to 5000x magnification
- 3D surface modeling

STRESS TESTING (THERMAL AND VIBRATION)

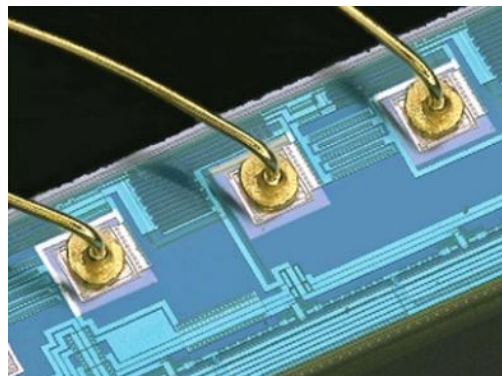
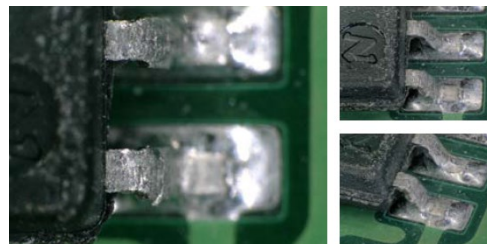
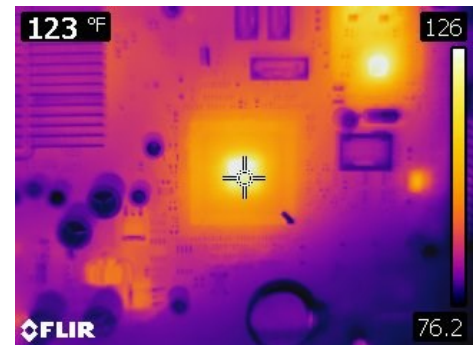
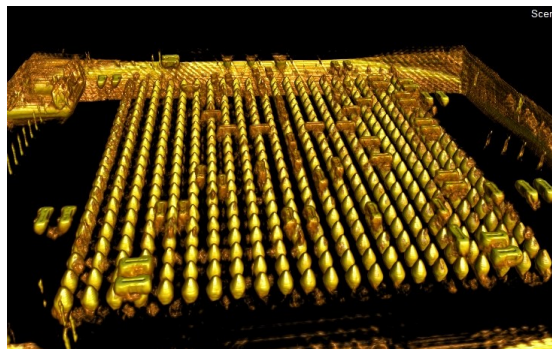
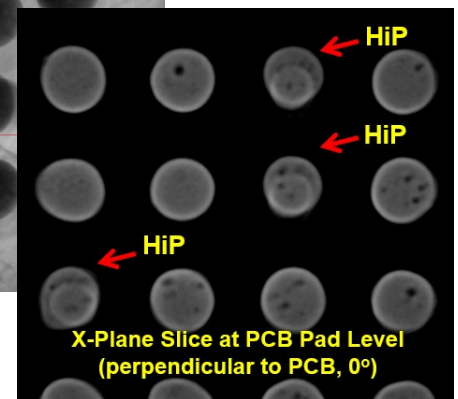
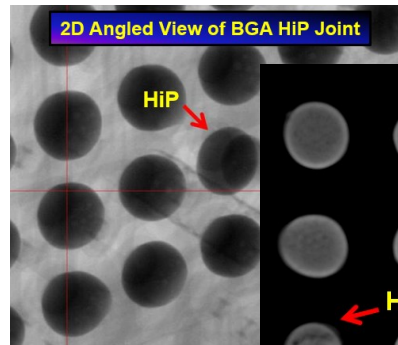
Vibration and Thermal (-80°C to +225°C) are compliant with all DO-160G requirements

ADVANCED FAILURE ANALYSIS

Utilizing proprietary analysis method

BENEFITS

- Reduce production problems
- Reduce NFF returns
- Identify mechanical root cause
- Improve designs
- Reduce cost
- Quick Turnaround
- Increase yields



MARKETS SERVED

- Aerospace
- Space
- Microelectronics
- Industrial
- Medical
- Consumer
- Engineering and R&D
- Production support